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FEATURES

JESD204B Subclass 0 or Subclass 1 coded serial digital outputs
 Signal-to-noise ratio (SNR) = 71.9 dBFS at 185 MHz AIN and
 250 MSPS with noise shaping requantizer (NSR) set to 33%
 Spurious-free dynamic range (SFDR) = 87 dBc at 185 MHz AIN
 and 250 MSPS

Total power consumption: 435 mW at 250 MSPS

1.8 V supply voltages

Integer 1 to 8 input clock divider

Sample rates of up to 250 MSPS

IF sampling frequencies of up to 400 MHz

Internal analog-to-digital converter (ADC) voltage reference

Flexible analog input range

1.4 V p-p to 2.0 V p-p (1.75 V p-p nominal)

ADC clock duty cycle stabilizer (DCS)

Serial port control

Energy saving power-down modes

APPLICATIONS

Communications

Diversity radio and smart antenna multiple input, multiple
 output (MIMO) systems

Multimode digital receivers (3G)

TD-SCDMA, WiMAX, W-CDMA, CDMA2000, GSM, EDGE, LTE

I/Q demodulation systems

General-purpose software radios

GENERAL DESCRIPTION

The AD6677 is an 11-bit, 250 MSPS, intermediate frequency (IF) receiver specifically designed to support multi-antenna systems in telecommunication applications where high dynamic range performance, low power, and small size are desired.

The device consists of a high performance ADC and an NSR digital block. The ADC consists of a multistage, differential pipelined architecture with integrated output error correction logic, and each ADC features a wide bandwidth switched capacitor sampling network within the first stage of the differential pipeline. An integrated voltage reference eases design considerations. A duty cycle stabilizer compensates for variations in the ADC clock duty cycle, allowing the converters to maintain excellent performance.

The ADC output is connected internally to an NSR block. The integrated NSR circuitry allows for improved SNR performance in a smaller frequency band within the Nyquist bandwidth. The device supports two different output modes selectable via the serial port interface (SPI). With the NSR feature enabled, the output of the ADC is processed such that the AD6677 supports enhanced SNR performance within a limited portion of the Nyquist bandwidth while maintaining an 11-bit output resolution.

FUNCTIONAL BLOCK DIAGRAM

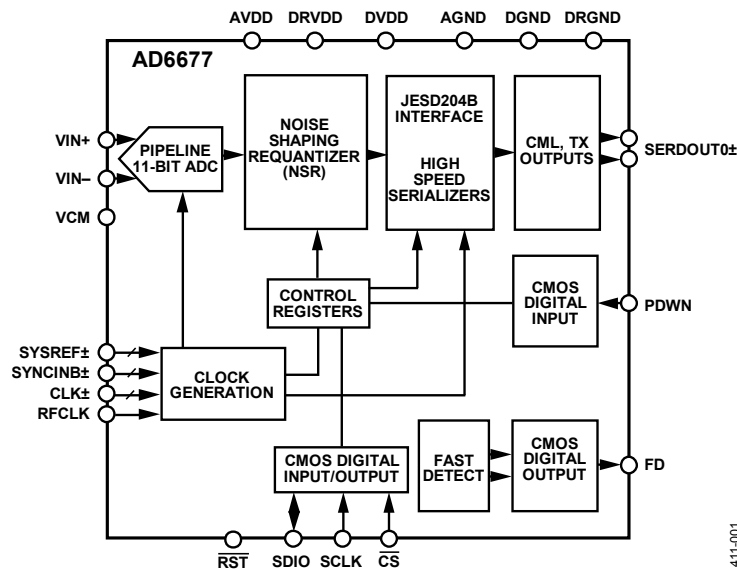


Figure 1.

11411-001

Rev. C

[Document Feedback](#)

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REVISION HISTORY

1/16—Rev. B to Rev. C

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5/14—Rev. A to Rev. B

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3/14—Rev. 0 to Rev. A

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4/13—Revision 0: Initial Version

The NSR block can be programmed to provide a bandwidth of either 22% or 33% of the sample clock. For example, with a sample clock rate of 250 MSPS, the AD6677 can achieve up to 76.3 dBFS SNR for a 55 MHz bandwidth in the 22% mode and up to 73.5 dBFS SNR for an 82 MHz bandwidth in the 33% mode.

When the NSR block is disabled, the ADC data is provided directly to the output at a resolution of 11 bits. The AD6677 can achieve up to 65.9 dBFS SNR for the entire Nyquist bandwidth when operated in this mode. This allows the AD6677 to be used in telecommunication applications such as a digital predistortion observation path where wider bandwidths are required.

The output data is routed directly to an external JESD204B serial output lane. This output is at current mode logic (CML) voltage levels. Only one JESD204B lane configuration such that the output coded data is sent through one lane ($L = 1$; $F = 4$). Synchronization input controls (SYNCINB \pm and SYSREF \pm) are provided.

The AD6677 receiver digitizes a wide spectrum of IF frequencies. This IF sampling architecture greatly reduces component cost and complexity compared with traditional analog techniques or less integrated digital methods.

Flexible power-down options allow significant power savings, when desired. Programmable overrange level detection is supported via dedicated fast detect pins.

Programming for setup and control is accomplished using a 3-wire SPI-compatible serial interface with numerous modes to support board level system testing.

The AD6677 is available in a 32-lead LFCSP and is specified over the industrial temperature range of -40°C to $+85^{\circ}\text{C}$.

PRODUCT HIGHLIGHTS

1. The configurable JESD204B output block with an integrated phase-locked loop (PLL) to support lane rates up to 5 Gbps.
2. The IF receiver includes an 11-bit, 250 MSPS ADC with programmable NSR function that allows for improved SNR within a reduced bandwidth of 22% or 33% of the sample rate.
3. Support for an optional radio frequency (RF) clock input to ease system board design.
4. Proprietary differential input maintains excellent SNR performance for input frequencies of up to 400 MHz.
5. An on-chip integer, 1-to-8 input clock divider and SYNC input allow synchronization of multiple devices.
6. Operation from a single 1.8 V power supply.
7. Standard SPI that supports various product features and functions, such as controlling the clock DCS, power-down, test modes, voltage reference mode, overrange fast detection, and serial output configuration.

SPECIFICATIONS

ADC DC SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, DVDD = 1.8 V, maximum sample rate, VIN = -1.0 dBFS differential input, 1.75 V p-p full-scale input range, duty cycle stabilizer enabled, default SPI, unless otherwise noted.

Table 1.

Parameter	Temperature	Min	Typ	Max	Unit
RESOLUTION	Full	11			Bits
ACCURACY					
No Missing Codes	Full		Guaranteed		
Offset Error	Full			±9.0	mV
Gain Error	Full	-5.3		+1.2	%FSR
Differential Nonlinearity (DNL)	Full			±0.6	LSB
	25°C		±0.25		LSB
Integral Nonlinearity (INL) ¹	Full			±0.7	LSB
	25°C		±0.3		LSB
TEMPERATURE DRIFT					
Offset Error	Full		±7		ppm/°C
Gain Error	Full		±39		ppm/°C
INPUT REFERRED NOISE					
VREF = 1.75 V	25°C		0.46		LSB rms
ANALOG INPUT					
Input Span	Full		1.75		V p-p
Input Capacitance ²	Full		2.5		pF
Input Resistance ³	Full		20		kΩ
Input Common-Mode Voltage	Full		0.9		V
POWER SUPPLIES					
Supply Voltage					
AVDD	Full	1.7	1.8	1.9	V
DRVDD	Full	1.7	1.8	1.9	V
DVDD	Full	1.7	1.8	1.9	V
Supply Current					
I _{AVDD}	Full		149	163	mA
I _{DRVDD + DVDD}	Full				mA
NSR Disabled	Full		93		mA
NSR Enabled, 22% Mode	Full		120	128	mA
NSR Enabled, 33% Mode	Full		129		mA
POWER CONSUMPTION					
Sine Wave Input	Full				
NSR Disabled	Full		435		mW
NSR Enabled, 22% Mode	Full		484		mW
NSR Enabled, 33% Mode	Full		500		mW
Standby Power ⁴	Full		266		mW
Power-Down Power ⁵	Full		9		mW

¹ Measured with a low input frequency, full-scale sine wave.

² Input capacitance refers to the effective capacitance between one differential input pin and the complement.

³ Input resistance refers to the effective resistance between one differential input pin and the complement.

⁴ Standby power is measured with a low input frequency, full-scale sine wave and the CLK± pins active. Address 0x08 is set to 0x20, and the PDWN pin is asserted.

⁵ Power-down power is measured with a low input frequency, full-scale sine wave, RFCLK pulled high, and the CLK± pins active. Address 0x08 is set to 0x00 and the PDWN pin is asserted.

ADC AC SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, DVDD = 1.8 V, maximum sample, VIN = -1.0 dBFS differential input, 1.75 V p-p full-scale input range, duty cycle stabilizer enabled, default SPI, unless otherwise noted.

Table 2.

Parameter ¹	Temperature	Min	Typ	Max	Unit
SIGNAL-TO-NOISE-RATIO (SNR)					
NSR Disabled					
$f_{IN} = 30$ MHz	25°C		66.6		dBFS
$f_{IN} = 90$ MHz	25°C		66.4		dBFS
$f_{IN} = 140$ MHz	25°C		66.2		dBFS
$f_{IN} = 185$ MHz	25°C		66.1		dBFS
	Full	65.8			dBFS
$f_{IN} = 220$ MHz	25°C		65.9		dBFS
NSR Enabled 22% Bandwidth Mode					
$f_{IN} = 30$ MHz	25°C		76.3		dBFS
$f_{IN} = 90$ MHz	25°C		75.7		dBFS
$f_{IN} = 140$ MHz	25°C		74.8		dBFS
$f_{IN} = 185$ MHz	25°C		74.2		dBFS
	Full	73.6			dBFS
$f_{IN} = 220$ MHz	25°C		73.6		dBFS
NSR Enabled 33% Bandwidth Mode					
$f_{IN} = 30$ MHz	25°C		73.5		dBFS
$f_{IN} = 90$ MHz	25°C		72.1		dBFS
$f_{IN} = 140$ MHz	25°C		72.6		dBFS
$f_{IN} = 185$ MHz	25°C		71.9		dBFS
	Full	70.6			dBFS
$f_{IN} = 220$ MHz	25°C		71.4		dBFS
SIGNAL-TO-NOISE AND DISTORTION (SINAD)					
$f_{IN} = 30$ MHz	25°C		65.6		dBFS
$f_{IN} = 90$ MHz	25°C		65.3		dBFS
$f_{IN} = 140$ MHz	25°C		65.2		dBFS
$f_{IN} = 185$ MHz	25°C		65.1		dBFS
	Full	64.7			dBFS
$f_{IN} = 220$ MHz	25°C		64.8		dBFS
EFFECTIVE NUMBER OF BITS (ENOB)					
$f_{IN} = 30$ MHz	25°C		10.6		Bits
$f_{IN} = 90$ MHz	25°C		10.6		Bits
$f_{IN} = 140$ MHz	25°C		10.5		Bits
$f_{IN} = 185$ MHz	25°C		10.5		Bits
$f_{IN} = 220$ MHz	25°C		10.5		Bits
WORST SECOND OR THIRD HARMONIC					
$f_{IN} = 30$ MHz	25°C		-87		dBc
$f_{IN} = 90$ MHz	25°C		-82		dBc
$f_{IN} = 140$ MHz	25°C		-86		dBc
$f_{IN} = 185$ MHz	25°C		-87		dBc
	Full			-80	dBc
$f_{IN} = 220$ MHz	25°C		-84		dBc

Parameter ¹	Temperature	Min	Typ	Max	Unit
SPURIOUS-FREE DYNAMIC RANGE (SFDR)					
$f_{IN} = 30$ MHz	25°C		87		dBc
$f_{IN} = 90$ MHz	25°C		82		dBc
$f_{IN} = 140$ MHz	25°C		86		dBc
$f_{IN} = 185$ MHz	25°C		87		dBc
	Full	80			dBc
$f_{IN} = 220$ MHz	25°C		84		dBc
WORST OTHER (HARMONIC OR SPUR)					
$f_{IN} = 30$ MHz	25°C		-94		dBc
$f_{IN} = 90$ MHz	25°C		-85		dBc
$f_{IN} = 140$ MHz	25°C		-88		dBc
$f_{IN} = 185$ MHz	25°C		-90		dBc
	Full			-82	dBc
$f_{IN} = 220$ MHz	25°C		-87		dBc
TWO-TONE SFDR					
$f_{IN1} = 184.12$ MHz (-7 dBFS), $f_{IN2} = 187.12$ MHz (-7 dBFS)	25°C		86		dBc
FULL POWER BANDWIDTH ²	25°C		1000		MHz

¹ See the Application Note [AN-835](#), *Understanding High Speed ADC Testing and Evaluation*, for a complete set of definitions.

² Full power bandwidth is the bandwidth of operation determined by where the spectral power of the fundamental frequency is reduced by 3 dB.

DIGITAL SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, DVDD = 1.8 V, maximum sample rate, VIN = -1.0 dBFS differential input, 1.75 V p-p full-scale input range, duty cycle stabilizer enabled, default SPI, unless otherwise noted.

Table 3.

Parameter	Temperature	Min	Typ	Max	Unit
DIFFERENTIAL CLOCK INPUTS (CLK+, CLK-)					
Input CLK± Clock Rate	Full	40		625	MHz
Logic Compliance			CMOS/LVDS/LVPECL		
Internal Common-Mode Bias	Full		0.9		V
Differential Input Voltage	Full	0.3		3.6	V p-p
Input Voltage Range	Full	AGND		AVDD	V
Input Common-Mode Range	Full	0.9		1.4	V
High Level Input Current	Full	0		+60	μA
Low Level Input Current	Full	-60		0	μA
Input Capacitance	Full		4		pF
Input Resistance	Full	8	10	12	kΩ
RF CLOCK INPUT (RFCLK)					
RF Clock Rate	Full	500		1500	MHz
Logic Compliance			CMOS/LVDS/LVPECL		
Internal Bias	Full		0.9		V
Input Voltage Range	Full	AGND		AVDD	V
High Input Voltage Level	Full	1.2		AVDD	V
Low Input Voltage Level	Full	AGND		0.6	V
High Level Input Current	Full	0		+150	μA
Low Level Input Current	Full	-150		0	μA
Input Capacitance	Full		1		pF
Input Resistance (AC-Coupled)	Full	8	10	12	kΩ

Parameter	Temperature	Min	Typ	Max	Unit
SYNCIN INPUTS (SYNCINB+/SYNCINB-)					
Logic Compliance			CMOS/LVDS		
Internal Common-Mode Bias	Full		0.9		V
Differential Input Voltage Range	Full	0.3		3.6	V p-p
Input Voltage Range	Full	DGND		DVDD	V
Input Common-Mode Range	Full	0.9		1.4	V
High Level Input Current	Full	-5		+5	μA
Low Level Input Current	Full	-10		+10	μA
Input Capacitance	Full		1		pF
Input Resistance	Full	12	16	20	kΩ
SYSREF INPUTS (SYSREF+, SYSREF-)					
Logic Compliance			LVDS		
Internal Common-Mode Bias	Full		0.9		V
Differential Input Voltage Range	Full	0.3		3.6	V p-p
Input Voltage Range	Full	AGND		AVDD	V
Input Common-Mode Range	Full	0.9		1.4	V
High Level Input Current	Full	-5		+5	μA
Low Level Input Current	Full	-10		+10	μA
Input Capacitance	Full		4		pF
Input Resistance	Full	8	10	12	kΩ
LOGIC INPUT (RST)¹					
High Level Input Voltage	Full	1.22		2.1	V
Low Level Input Voltage	Full	0		0.6	V
High Level Input Current	Full	-5		+5	μA
Low Level Input Current	Full	-100		-45	μA
Input Resistance	Full		26		kΩ
Input Capacitance	Full		2		pF
LOGIC INPUTS (SCLK, PDWN, CS²)³					
High Level Input Voltage	Full	1.22		2.1	V
Low Level Input Voltage	Full	0		0.6	V
High Level Input Current	Full	45		100	μA
Low Level Input Current	Full	-10		+10	μA
Input Resistance	Full		26		kΩ
Input Capacitance	Full		2		pF
LOGIC INPUT (SDIO)³					
High Level Input Voltage	Full	1.22		2.1	V
Low Level Input Voltage	Full	0		0.6	V
High Level Input Current	Full	45		100	μA
Low Level Input Current	Full	-10		+10	μA
Input Resistance	Full		26		kΩ
Input Capacitance	Full		5		pF
DIGITAL OUTPUTS (SERDOUT0+/SERDOUT0-)					
Logic Compliance			CML		
Differential Output Voltage (V _{OD})	Full	400	600	750	mV
Output Offset Voltage (V _{OS})	Full	0.75	DRVDD/2	1.05	V
DIGITAL OUTPUTS (SDIO/FD)⁴					
High Level Output Voltage (V _{OH})	Full				V
I _{OH} = 50 μA	Full	1.79			V
I _{OH} = 0.5 mA	Full	1.75			V
I _{OH} = 2.0 mA	Full	1.6			V

Parameter	Temperature	Min	Typ	Max	Unit
Low Level Output Voltage (V_{OL})	Full				
$I_{OL} = 2.0 \text{ mA}$	Full			0.25	V
$I_{OL} = 1.6 \text{ mA}$	Full			0.2	V
$I_{OL} = 50 \text{ }\mu\text{A}$	Full			0.05	V

¹ Pull-up.

² Needs an external pull-up.

³ Pull-down.

⁴ Compatible with JEDEC standard JESD8-7A.

SWITCHING SPECIFICATIONS

Table 4.

Parameter	Symbol	Temperature	Min	Typ	Max	Unit
CLOCK INPUT PARAMETERS						
Conversion Rate ¹	f_s	Full	40		250	MSPS
SYSREF \pm Setup Time to Rising Edge CLK \pm ²	t_{REFS}	Full		300		ps
SYSREF \pm Hold Time from Rising Edge CLK \pm ²	t_{REFH}	Full		40		ps
SYSREF \pm Setup Time to Rising Edge RFCLK \pm ²	t_{REFSRF}	Full		400		ps
SYSREF \pm Hold Time from Rising Edge RFCLK \pm ²	t_{REFHRF}	Full		0		ps
CLK \pm Pulse Width High	t_{CH}					
Divide by 1 Mode, DCS Enabled		Full	1.8	2.0	2.2	ns
Divide by 1 Mode, DCS Disabled		Full	1.9	2.0	2.1	ns
Divide by 2 Mode Through Divide by 8 Mode		Full	0.8			ns
Aperture Delay	t_A	Full		1.0		ns
Aperture Uncertainty (Jitter)	t_J	Full		0.16		ps rms
DATA OUTPUT PARAMETERS						
Data Output Period or Unit Interval (UI)		Full		$20 \times f_s$		Seconds
Data Output Duty Cycle		25°C		50		%
Data Valid Time		25°C		0.78		UI
PLL Lock Time	t_{LOCK}	25°C		25		μs
Wake-Up						
Time (Standby)		25°C		10		μs
Time ADC (Power-Down) ³		25°C		250		ms
Time Output (Power-Down) ⁴		25°C		50		ms
Subclass 0: SYNCINB \pm Falling Edge to First Valid K.28 Characters (Delay Required for Rx CGS Start)		Full	5			Multiframe
Subclass 1: SYSREF \pm Rising Edge to First Valid K.28 Characters (Delay Required for SYNCB \pm Rising Edge/Rx CGS Start)		Full	6			Multiframe
CGS Phase K.28 Characters Duration		Full	1			Multiframe
Pipeline Delay						
JESD204B (Latency)		Full		36		Cycles ⁵
Additional Pipeline Latency with NSR Enabled		Full		2		Cycles
Fast Detect (Latency)		Full		7		Cycles
Lane Rate		Full			5	Gbps
Uncorrelated Bounded High Probability (UBHP) Jitter		Full		12		ps
Random Jitter at 5 Gbps		Full		1.7		ps rms
Output Rise/Fall Time		Full		60		ps
Differential Termination Resistance		25°C		100		Ω
Out of Range Recovery Time		Full		3		Cycles

¹ Conversion rate is the clock rate after the divider.

² Refer to Figure 3 for timing diagram.

³ Wake-up time ADC is defined as the time required for the ADC to return to normal operation from power-down mode.

⁴ Wake-up time output is defined as the time required for JESD204B output to return to normal operation from power-down mode.

⁵ Cycles refers to ADC conversion rate cycles.

TIMING SPECIFICATIONS

Table 5.

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
SPI TIMING REQUIREMENTS (See Figure 58)					
t_{DS}	Setup time between the data and the rising edge of SCLK	2			ns
t_{DH}	Hold time between the data and the rising edge of SCLK	2			ns
t_{CLK}	Period of the SCLK	40			ns
t_S	Setup time between \overline{CS} and SCLK	2			ns
t_H	Hold time between \overline{CS} and SCLK	2			ns
t_{HIGH}	Minimum period that SCLK must be in a logic high state	10			ns
t_{LOW}	Minimum period that SCLK must be in a logic low state	10			ns
t_{EN_SDIO}	Time required for the SDIO pin to switch from an input to an output relative to the SCLK falling edge (not shown in figures)	10			ns
t_{DIS_SDIO}	Time required for the SDIO pin to switch from an output to an input relative to the SCLK rising edge (not shown in figures)	10			ns
t_{SPL_RST}	Time required after hard or soft reset until SPI access is available (not shown in figures)	500			μs

Timing Diagrams

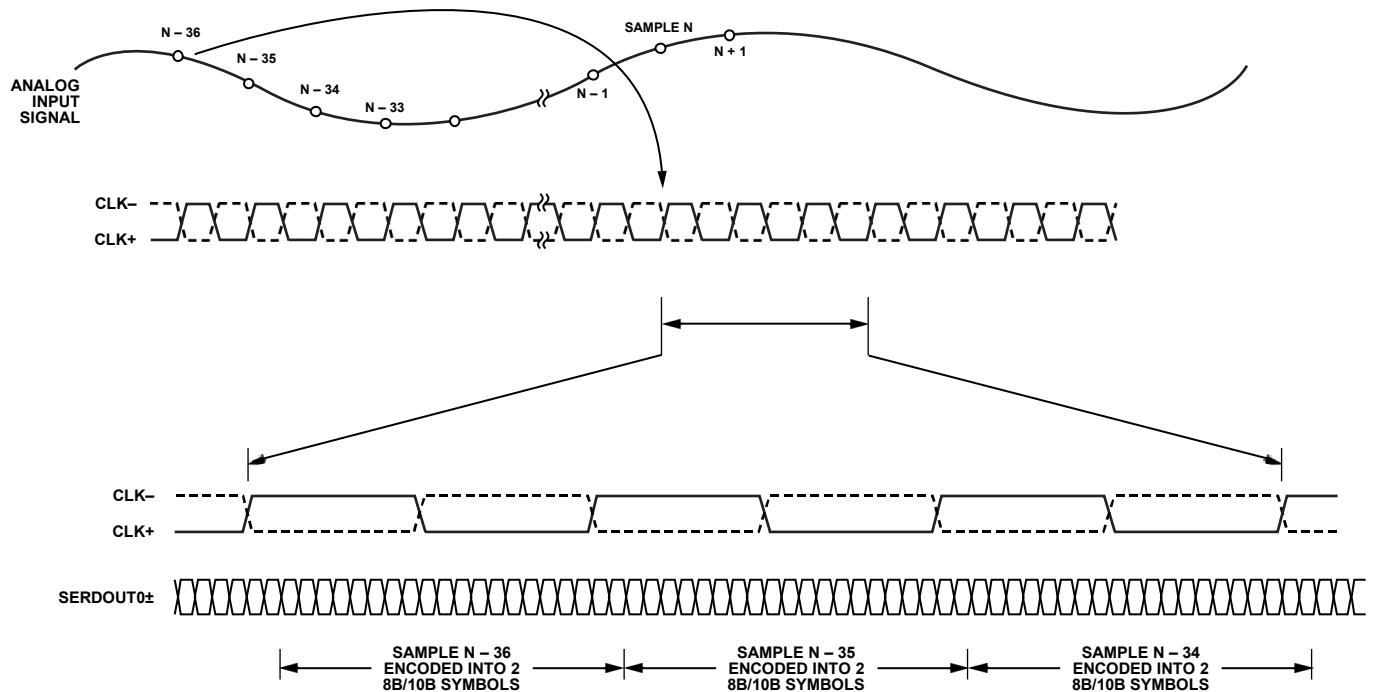
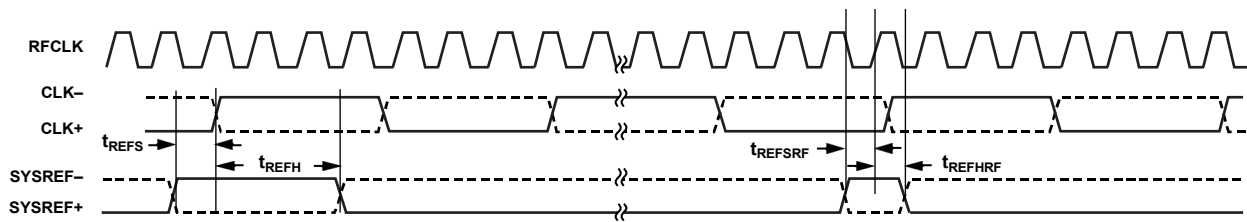


Figure 2. Data Output Timing



NOTES
1. CLOCK INPUT IS EITHER RFCLK OR CLK±, NOT BOTH.

Figure 3. SYSREF± Setup and Hold Timing (Clock Input Either RFCLK or CLK±, Not Both)

ABSOLUTE MAXIMUM RATINGS

Table 6.

Parameter	Rating
Electrical	
AVDD to AGND	−0.3 V to +2.0 V
DRVDD to DRGND	−0.3 V to +2.0 V
DVDD to DGND	−0.3 V to +2.0 V
VIN+, VIN− to AGND	−0.3 V to AVDD + 0.2 V
CLK+, CLK− to AGND	−0.3 V to AVDD + 0.2 V
RFCLK to AGND	−0.3 V to AVDD + 0.2 V
VCM to AGND	−0.3 V to AVDD + 0.2 V
\overline{CS} , PDWN to DGND	−0.3 V to DVDD + 0.3 V
SCLK to DGND	−0.3 V to DVDD + 0.3 V
SDIO to DGND	−0.3 V to DVDD + 0.3 V
\overline{RST} to DGND	−0.3 V to DVDD + 0.3 V
FD to DGND	−0.3 V to DVDD + 0.3 V
SERDOUT0+, SERDOUT0− to AGND	−0.3 V to DRVDD + 0.3 V
SYNCINB+, SYNCINB− to DGND	−0.3 V to DVDD + 0.3 V
SYSREF+, SYSREF− to AGND	−0.3 V to AVDD + 0.3 V
Environmental	
Operating Temperature Range (Ambient)	−40°C to +85°C
Maximum Junction Temperature Under Bias	150°C
Storage Temperature Range (Ambient)	−65°C to +125°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL CHARACTERISTICS

The exposed pad must be soldered to the ground plane of the LFCSP package. This increases the reliability of the solder joints, maximizing the thermal capability of the package.

Table 7. Thermal Resistance

Package Type	Airflow Velocity (m/sec)	θ_{JA} ^{1,2}	θ_{JC} ^{1,3,4}	θ_{JB} ^{1,4,5}	Unit
32-Lead LFCSP 5 mm × 5 mm (CP-32-12)	0	37.1	3.1	20.7	°C/W
	1.0	32.4	N/A	N/A	°C/W
	2.5	29.1	N/A	N/A	°C/W

¹ Per JEDEC 51-7, plus JEDEC 25-5 2S2P test board.

² Per JEDEC JESD51-2 (still air) or JEDEC JESD51-6 (moving air).

³ Per MIL-STD-883, Method 1012.1.

⁴ N/A means not applicable.

⁵ Per JEDEC JESD51-8 (still air).

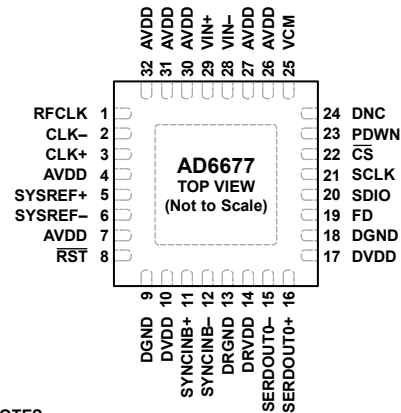
Typical θ_{JA} is specified for a 4-layer printed circuit board (PCB) with a solid ground plane. As shown in Table 7, airflow increases heat dissipation, which reduces θ_{JA} . In addition, metal in direct contact with the package leads from metal traces, through holes, ground, and power planes reduces the θ_{JA} .

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



NOTES

1. DNC = DO NOT CONNECT. DO NOT CONNECT TO THIS PIN.
2. THE EXPOSED THERMAL PADDLE ON THE BOTTOM OF THE PACKAGE PROVIDES THE GROUND REFERENCE FOR AVDD. THIS EXPOSED PAD MUST BE CONNECTED TO AGND FOR PROPER OPERATION.

11471-004

Figure 4. Pin Configuration (Top View)

Table 8. Pin Function Descriptions

Pin No.	Mnemonic	Type	Description
ADC Power Supplies 4, 7, 26, 27, 30, 31, 32 9, 18 10, 17 13 14 24	AVDD DGND DVDD DRGND DRVDD DNC EPAD (AGND)	Supply Ground Supply Ground Supply Ground	Analog Power Supply (1.8 V Nominal). Ground Reference for DVDD. Digital Power Supply (1.8 V Nominal). Ground Reference for DRVDD. JESD204B PHY Serial Output Driver Supply (1.8 V Nominal). Note that the DRVDD power is referenced to the AGND plane. Do Not Connect. Expose Pad. The exposed thermal pad on the bottom of the package provides the ground reference for AVDD. This exposed pad must be connected to AGND for proper operation.
ADC Analog 1 2 3 25 28 29	RFCLK CLK- CLK+ VCM VIN- VIN+	Input Input Input Output Input Input	ADC RF Clock Input. ADC Nyquist Clock Input—Complement. ADC Nyquist Clock Input—True. Common-Mode Level Bias Output for Analog Inputs. Decouple this pin to ground using a 0.1 μ F capacitor. Differential Analog Input (Negative). Differential Analog Input (Positive).
ADC Fast Detect Output 19	FD	Output	Fast Detect Indicator (CMOS Levels).
Digital Inputs 5 6 11 12	SYSREF+ SYSREF- SYNCINB+ SYNCINB-	Input Input Input Input	JESD204B LVDS SYSREF Input—True. JESD204B LVDS SYSREF Input—Complement. JESD204B LVDS Sync Input—True/JESD204B CMOS Sync Input. JESD204B LVDS Sync Input—Complement.
Data Outputs 15 16	SERDOUT0- SERDOUT0+	Output Output	CML Output Data—Complement. CML Output Data—True.

Pin No.	Mnemonic	Type	Description
Device Under Test (DUT) Controls			
8	$\overline{\text{RST}}$	Input	Digital Reset (Active Low).
20	SDIO	Input/output	SPI Serial Data Input/Output.
21	SCLK	Input	SPI Serial Clock.
22	$\overline{\text{CS}}$	Input	SPI Chip Select (Active Low). This pin needs an external pull-up.
23	PDWN	Input	Power-Down Input (Active High). The operation of this pin depends on SPI mode and can be configured as power-down or standby (see Table 17).

TYPICAL PERFORMANCE CHARACTERISTICS

AVDD = 1.8 V, DRVDD = 1.8 V, DVDD = 1.8 V, sample rate is 250 MSPS, duty cycle stabilizer enabled, 1.75 V p-p differential input, VIN = -1.0 dBFS, 16k sample, TA = 25°C, default SPI, unless otherwise noted.

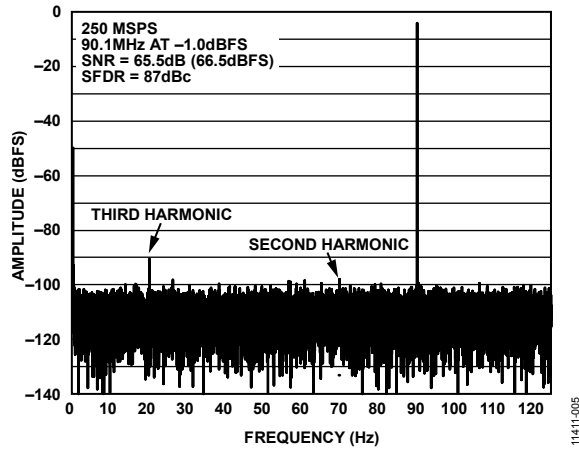


Figure 5. Single-Tone FFT with $f_{IN} = 90.1$ MHz

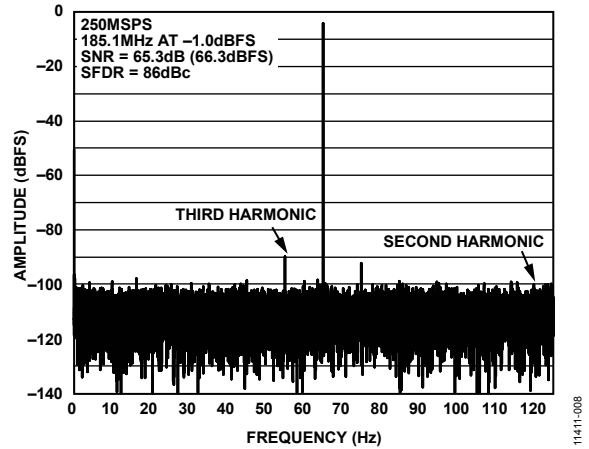


Figure 8. Single-Tone FFT with $f_{IN} = 185.1$ MHz, RFCLK = 1.0 GHz with Divide by 4 (Address 0x09 = 0x21)

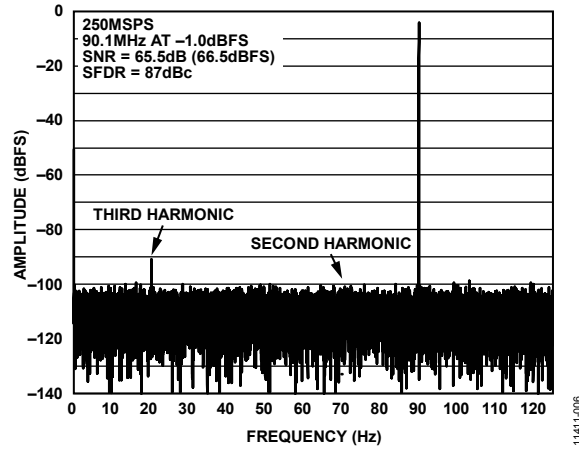


Figure 6. Single-Tone FFT with $f_{IN} = 90.1$ MHz, RFCLK = 1.0 GHz with Divide by 4 (Address 0x09 = 0x21)

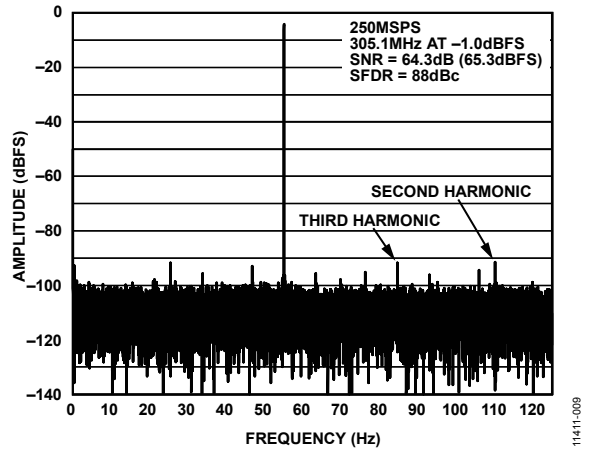


Figure 9. Single-Tone FFT with $f_{IN} = 305.1$ MHz

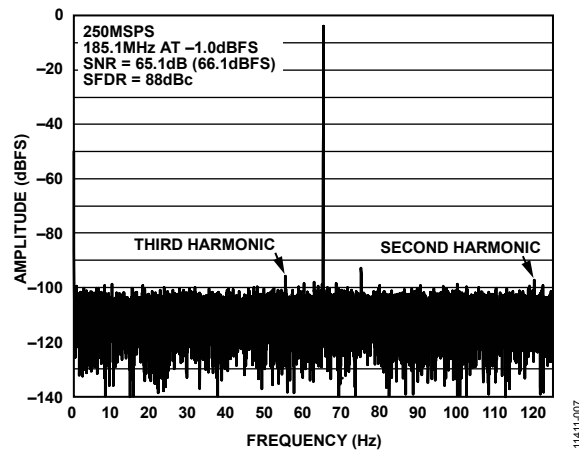


Figure 7. Single-Tone FFT with $f_{IN} = 185.1$ MHz

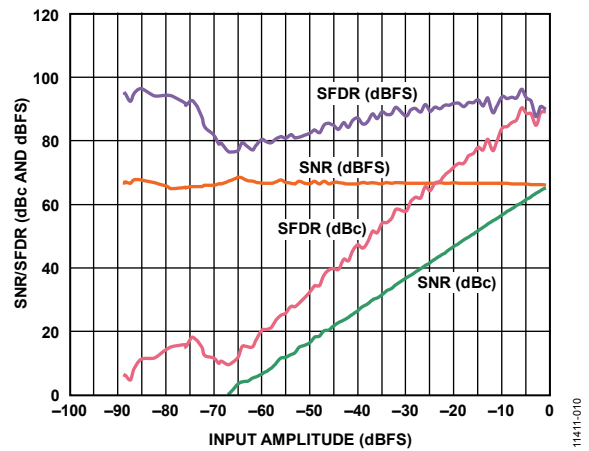


Figure 10. Single-Tone SNR/SFDR vs. Input Amplitude (A_{IN}) with $f_{IN} = 185.1$ MHz

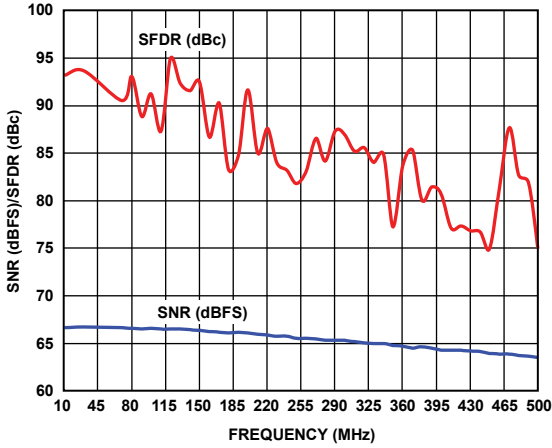


Figure 11. Single-Tone SNR/SFDR vs. Input Frequency (f_{IN})

11411-011

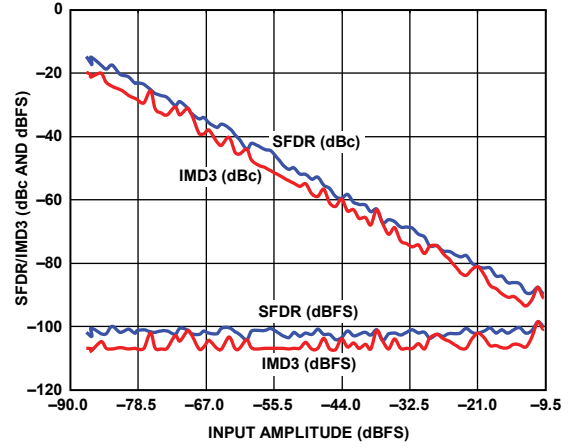


Figure 14. Two-Tone SFDR/IMD3 vs. Input Amplitude (A_{IN}) with $f_{IN1} = 184.12$ MHz, $f_{IN2} = 187.12$ MHz

11411-114

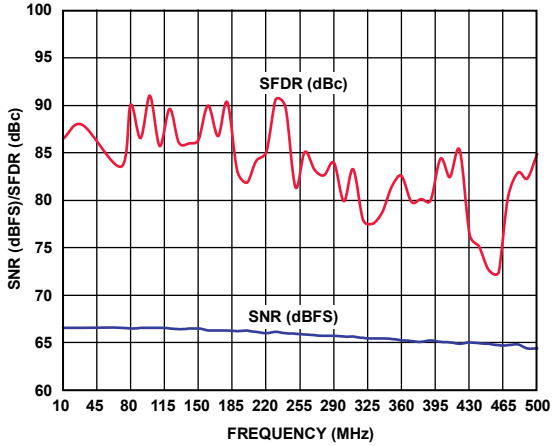


Figure 12. Single-Tone SNR/SFDR vs. Input Frequency (f_{IN}), RFCLK = 1.0 GHz with Divide by 4 (Address 0x09 = 0x21)

11411-012

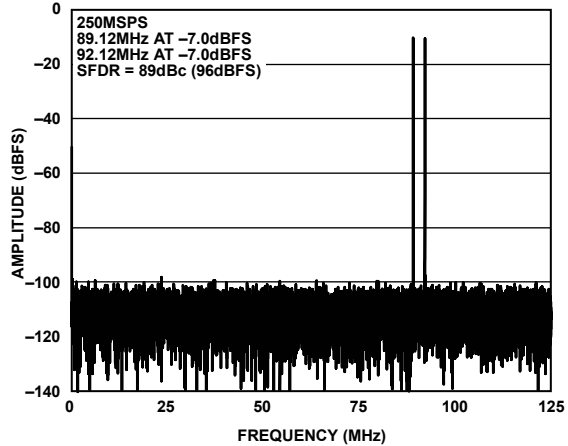


Figure 15. Two-Tone FFT with $f_{IN1} = 89.12$ MHz, $f_{IN2} = 92.12$ MHz

11411-015

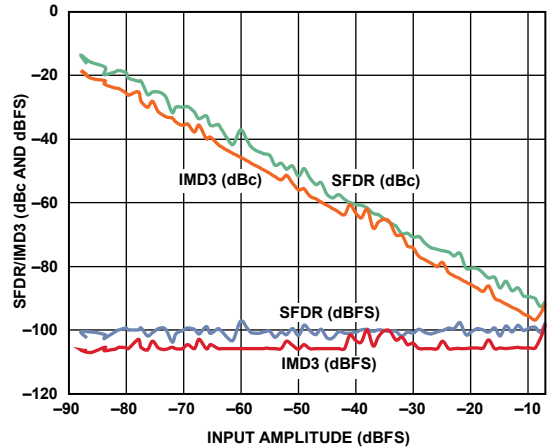


Figure 13. Two-Tone SFDR/IMD3 vs. Input Amplitude (A_{IN}) with $f_{IN1} = 89.12$ MHz, $f_{IN2} = 92.12$ MHz

11411-013

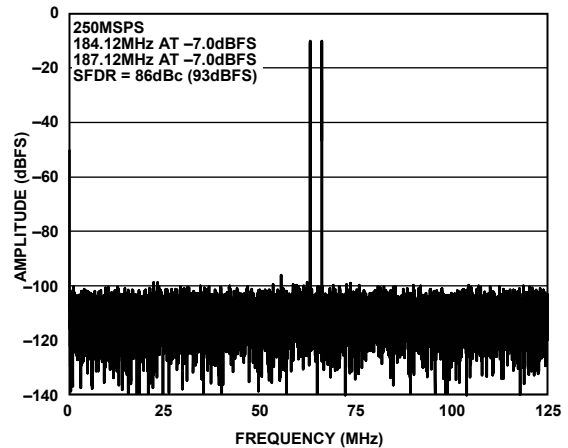


Figure 16. Two-Tone FFT with $f_{IN1} = 184.12$ MHz, $f_{IN2} = 187.12$ MHz

11411-016

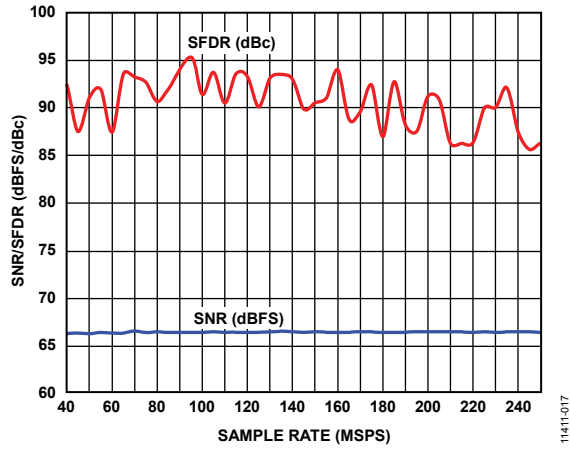


Figure 17. Single-Tone SNR/SFDR vs. Sample Rate (f_s) with $f_{IN} = 90.1$ MHz

11411-017

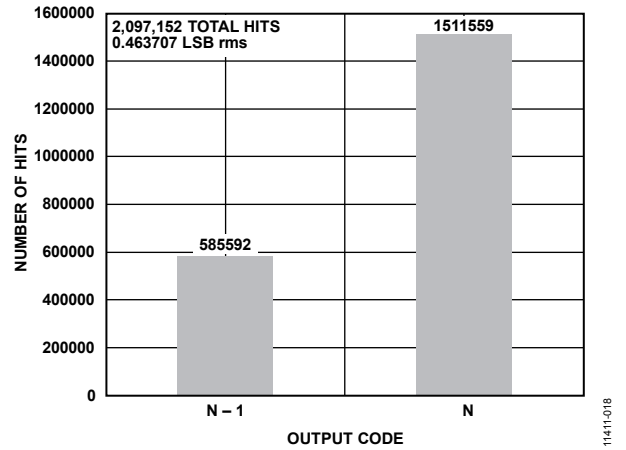


Figure 18. Grounded Input Histogram

11411-018

EQUIVALENT CIRCUITS

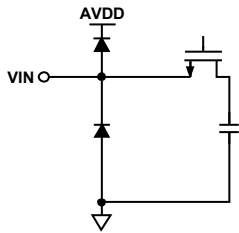


Figure 19. Equivalent Analog Input Circuit

11411-019

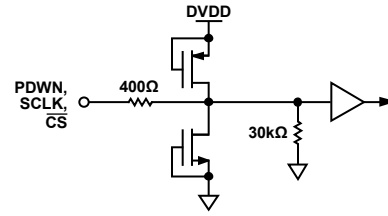


Figure 24. Equivalent PDWN, SCLK, or \overline{CS} Input Circuit

11411-024

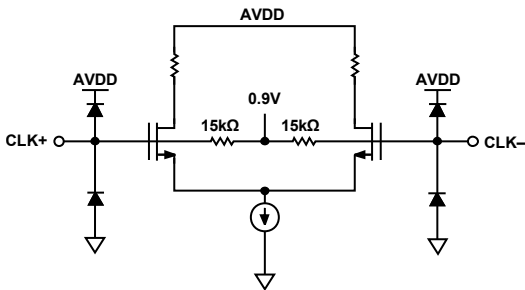


Figure 20. Equivalent Clock Input Circuit

11411-020

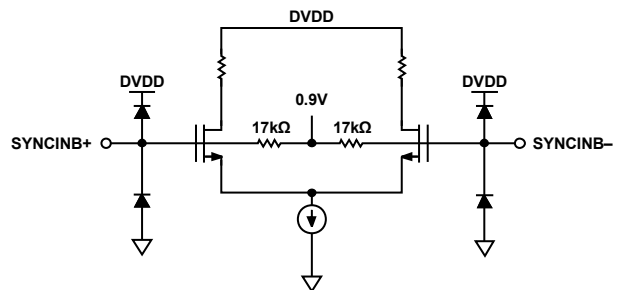


Figure 25. Equivalent SYNCINB± Input Circuit

11411-025

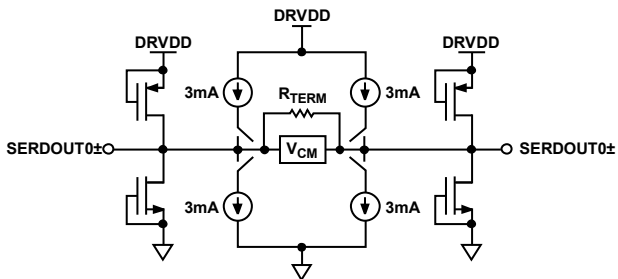


Figure 21. Digital CML Output Circuit

11411-022

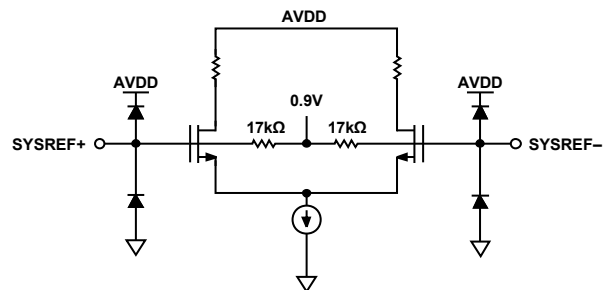


Figure 26. Equivalent SYSREF± Input Circuit

11411-026

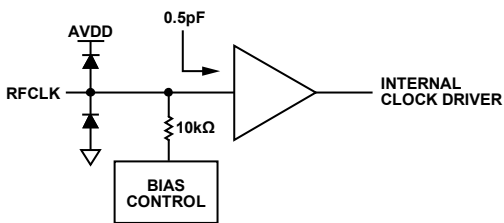


Figure 22. Equivalent RF Clock Input Circuit

11411-021

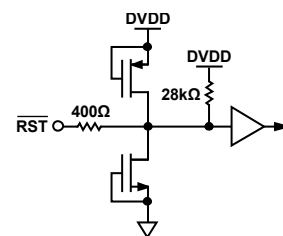


Figure 27. Equivalent \overline{RST} Input Circuit

11411-027

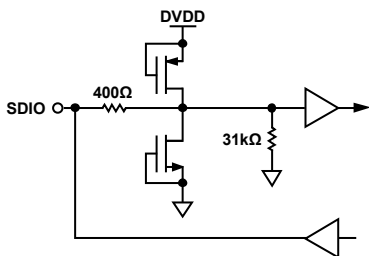


Figure 23. Equivalent SDIO Circuit

11411-023

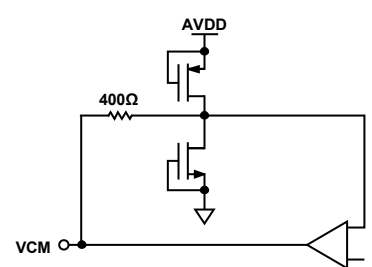


Figure 28. Equivalent VCM Circuit

11411-028

THEORY OF OPERATION

The AD6677 has one analog input channel and one JESD204B output lane. The signal passes through several stages before appearing at the output port.

The dual ADC design can be used for diversity reception of signals, where the ADCs operate identically on the same carrier but from two separate antennae. The ADCs can also operate with independent analog inputs. The user can sample frequencies from dc to 400 MHz using appropriate low-pass or band-pass filtering at the ADC inputs with little loss in ADC performance. Operation above 400 MHz analog input is permitted but occurs at the expense of increased ADC noise and distortion.

A synchronization capability is provided to allow synchronized timing between multiple devices.

Programming and control of the AD6677 are accomplished using a 3-pin, SPI-compatible serial interface.

ADC ARCHITECTURE

The AD6677 architecture consists of a front-end, sample-and-hold circuit, followed by a pipelined switched capacitor ADC. The quantized outputs from each stage are combined into a final 11-bit result in the digital correction logic. Alternately, the 11-bit result can be processed through the NSR block before it is sent to the digital correction logic.

The pipelined architecture permits the first stage to operate on a new input sample, and the remaining stages to operate on the preceding samples. Sampling occurs on the rising edge of the clock.

Each stage of the pipeline, excluding the last, consists of a low resolution flash ADC connected to a switched capacitor digital-to-analog converter (DAC) and an interstage residue amplifier (MDAC). The MDAC magnifies the difference between the reconstructed DAC output and the flash input for the next stage in the pipeline. One bit of redundancy is used in each stage to facilitate digital correction of flash errors. The last stage simply consists of a flash ADC.

The input stage contains a differential sampling circuit that can be ac- or dc-coupled in differential or single-ended modes. The output staging block aligns the data, corrects errors, and passes the data to the output buffers. The output buffers are powered from a separate supply, allowing digital output noise to be separated from the analog core.

The user can input frequencies from dc to 300 MHz using appropriate low-pass or band-pass filtering at the ADC inputs, with little loss in performance. Operation to a 400 MHz analog input is permitted; however, it occurs at the expense of increased ADC noise and distortion. A synchronization capability is provided to allow synchronized timing between multiple devices. Programming and control of the AD6677 are accomplished using a 3-wire SPI-compatible serial interface.

ANALOG INPUT CONSIDERATIONS

The analog input to the AD6677 is a differential, switched capacitor circuit that has been designed for optimum performance while processing a differential input signal.

The clock signal alternatively switches the input between sample mode and hold mode (see the configuration shown in Figure 29). When the input is switched into sample mode, the signal source must be capable of charging the sampling capacitors and settling within 1/2 clock cycle.

A small resistor in series with each input can help reduce the peak transient current required from the output stage of the driving source. A shunt capacitor can be placed across the inputs to provide dynamic charging currents. This passive network creates a low-pass filter at the ADC input; therefore, the precise values are dependent on the application.

In IF undersampling applications, reduce the shunt capacitors. In combination with the driving source impedance, the shunt capacitors limit the input bandwidth. Refer to the Application Note AN-742, *Frequency Domain Response of Switched-Capacitor ADCs*; the Application Note AN-827, *A Resonant Approach to Interfacing Amplifiers to Switched-Capacitor ADCs*; and the *Analog Dialogue* article, “Transformer-Coupled Front-End for Wideband A/D Converters,” for more information.

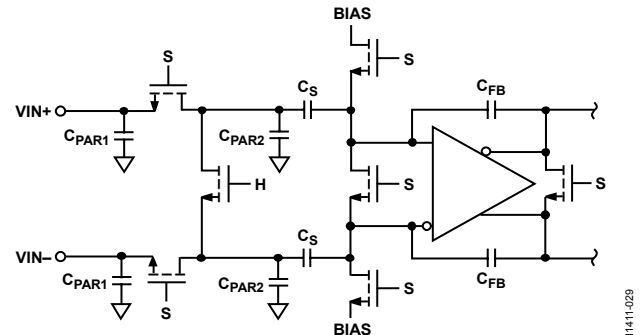


Figure 29. Switched Capacitor Input

For best dynamic performance, match the source impedances driving VIN+ and VIN- and differentially balance the inputs.

Input Common Mode

The analog inputs of the AD6677 are not internally dc biased. In ac-coupled applications, the user must provide this bias externally. Configuring the input so that $V_{CM} = 0.5 \times AVDD$ (or 0.9 V) is recommended for optimum performance. An on-board common-mode voltage reference is included in the design and is available from the VCM pin. Using the VCM output to set the input common mode is recommended. Optimum performance is achieved when the common-mode voltage of the analog input is set by the VCM pin voltage (typically $0.5 \times AVDD$). Decouple the VCM pin to ground by using a 0.1 μF capacitor, as described in the Applications Information section. Place this decoupling capacitor close to the pin to minimize the series resistance and inductance between the device and this capacitor.

Differential Input Configurations

Optimum performance is achieved while driving the AD6677 in a differential input configuration. For baseband applications, the AD8138, ADA4937-1, ADA4938-1, and ADA4930-1 differential drivers provide excellent performance and a flexible interface to the ADC.

The output common-mode voltage of the ADA4930-1 is easily set with the VCM pin of the AD6677 (see Figure 30), and the driver can be configured in a Sallen-Key filter topology to provide band limiting of the input signal.

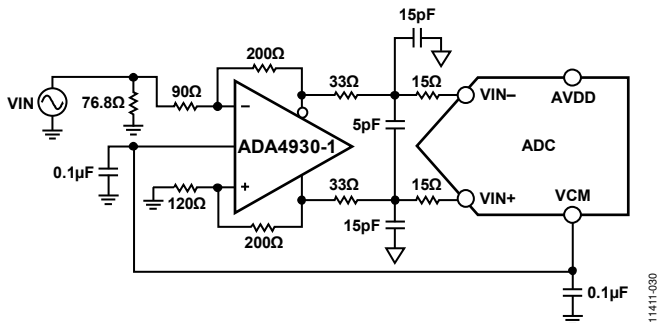


Figure 30. Differential Input Configuration Using the ADA4930-1

For baseband applications where SNR is a key parameter, differential transformer coupling is the recommended input configuration. An example is shown in Figure 31. To bias the analog input, the VCM voltage can be connected to the center tap of the secondary winding of the transformer.

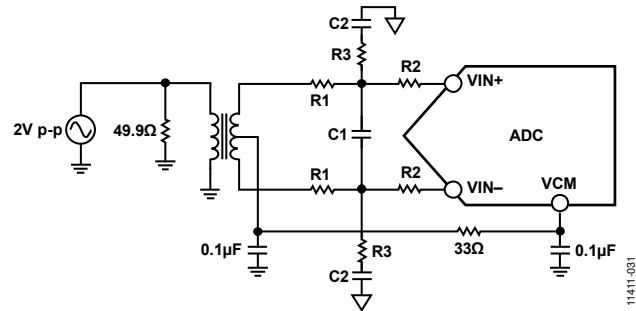


Figure 31. Differential Transformer-Coupled Configuration

Consider the signal characteristics when selecting a transformer. Most RF transformers saturate at frequencies below a few megahertz. Excessive signal power can also cause core saturation, which leads to distortion.

At input frequencies in the second Nyquist zone and above, the noise performance of most amplifiers is not adequate to achieve the true SNR performance of the AD6677. For applications where SNR is a key parameter, differential double balun coupling is the recommended input configuration (see Figure 32). In this configuration, the input is ac-coupled and the VCM voltage is provided to each input through a 33 Ω resistor. These resistors compensate for losses in the input baluns to provide a 50 Ω impedance to the driver.

In the double balun and transformer configurations, the value of the input capacitors and resistors is dependent on the input frequency and source impedance. Based on these parameters, the value of the input resistors and capacitors may need to be adjusted or some components may need to be removed. Table 9 displays recommended values to set the RC network for different input frequency ranges. However, these values are dependent on the input signal and bandwidth and must only be used as a starting guide. Note that the values given in Table 9 are for each R1, R2, C1, C2, and R3 components shown in Figure 31 and Figure 32.

Table 9. Example RC Network

Frequency Range (MHz)	R1 Series (Ω)	C1 Differential (pF)	R2 Series (Ω)	C2 Shunt (pF)	R3 Shunt (Ω)
0 to 100	33	8.2	0	15	24.9
100 to 400	15	8.2	0	8.2	24.9
>400	15	≤ 3.9	0	≤ 3.9	24.9

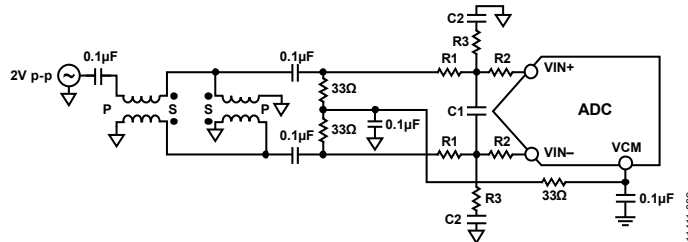
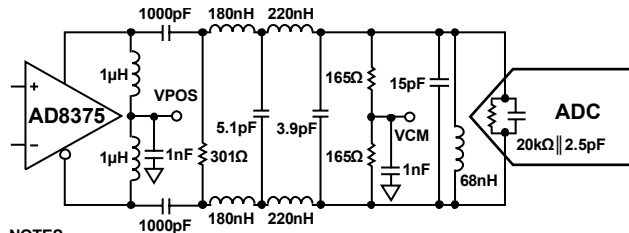


Figure 32. Differential Double Balun Input Configuration

An alternative to using a transformer-coupled input at frequencies in the second Nyquist zone is to use an amplifier with variable gain. The **AD8375** digital variable gain amplifier (DVGA) provides good performance for driving the **AD6677**. Figure 33 shows an example of the **AD8375** driving the **AD6677** through a band-pass antialiasing filter.



- NOTES
1. ALL INDUCTORS ARE COILCRAFT® 0603CS COMPONENTS WITH THE EXCEPTION OF THE 1μH CHOKE INDUCTORS (COILCRAFT 0603LS).
 2. FILTER VALUES SHOWN ARE FOR A 20MHz BANDWIDTH FILTER CENTERED AT 140MHz.

Figure 33. Differential Input Configuration Using the **AD8375**

VOLTAGE REFERENCE

A stable and accurate voltage reference is built into the **AD6677**. The full-scale input range can be adjusted by varying the reference voltage via the SPI. The input span of the ADC tracks the reference voltage changes linearly.

CLOCK INPUT CONSIDERATIONS

The **AD6677** has two options for deriving the input sampling clock: a differential Nyquist sampling clock input or an RF clock input (which is internally divided by 2 or 4). The clock input is selected in Address 0x09 and, by default, is configured for the Nyquist clock input. For optimum performance, clock the **AD6677** Nyquist sample clock input, CLK+ and CLK–, with a differential signal. The signal is typically ac-coupled into the CLK+ and CLK– pins via a transformer or capacitors. These pins are biased internally (see Figure 34) and require no external bias. If the clock inputs are floated, CLK– is pulled slightly lower than CLK+ to prevent spurious clocking.

Nyquist Clock Input Options

The **AD6677** Nyquist clock input supports a differential clock between 40 MHz to 625 MHz. The clock input structure supports differential input voltages from 0.3 V to 3.6 V and is, therefore, compatible with various logic family inputs, such as CMOS, LVDS, and LVPECL. A sine wave input is also accepted, but higher slew rates typically provide optimal performance. Clock source jitter is a critical parameter that can affect performance, as described in the Jitter Considerations section. If the inputs are floated, pull the CLK– pin low to prevent spurious clocking.

The Nyquist clock input pins, CLK+ and CLK–, are internally biased to 0.9 V and have a typical input impedance of 4 pF in parallel with 10 kΩ (see Figure 34). The input clock is typically ac-coupled to CLK+ and CLK–. Some typical clock drive circuits are presented in Figure 35 through Figure 38 for reference.

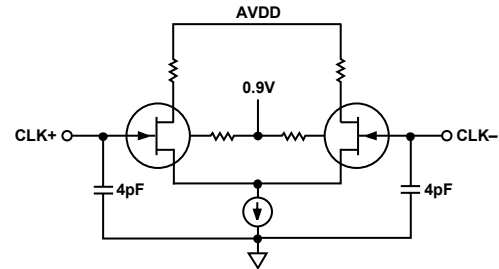


Figure 34. Equivalent Nyquist Clock Input Circuit

For applications where a single-ended low jitter clock between 40 MHz to 200 MHz is available, an RF transformer is recommended. Figure 35 shows an example of using an RF transformer in the clock network. At frequencies above 200 MHz, an RF balun is recommended, as seen in Figure 36. The back to back Schottky diodes across the transformer secondary limit clock excursions into the **AD6677** to approximately 0.8 V p-p differential. This limit helps prevent the large voltage swings of the clock from feeding through to other portions of the **AD6677**, yet preserves the fast rise and fall times of the clock, which are critical to low jitter performance.

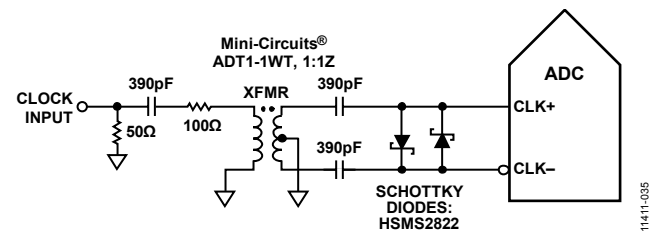


Figure 35. Transformer-Coupled Differential Clock (Up to 200 MHz)

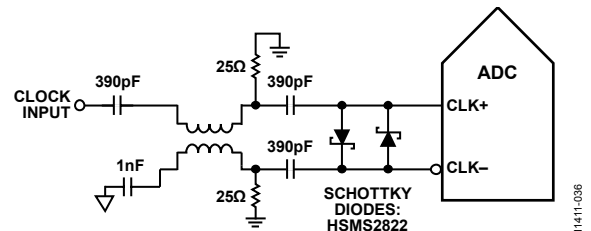


Figure 36. Balun-Coupled Differential Clock (Up to 625 MHz)

In some cases, it is desirable to buffer or generate multiple clocks from a single source. In those cases, Analog Devices, Inc., offers clock drivers with excellent jitter performance. Figure 37 shows a typical PECL driver circuit that uses PECL drivers such as the **AD9510**, **AD9511**, **AD9512**, **AD9513**, **AD9514**, **AD9515**, the **AD9516-0** through **AD9516-5** device family, the **AD9517-0** through **AD9517-4** device family, the **AD9518-0** through **AD9518-4** device family, the **AD9520-0** through **AD9520-5** device family, the **AD9522-0** through **AD9522-5** device family, **AD9523**, **AD9524**, and **ADCLK905/ADCLK907/ADCLK925**.

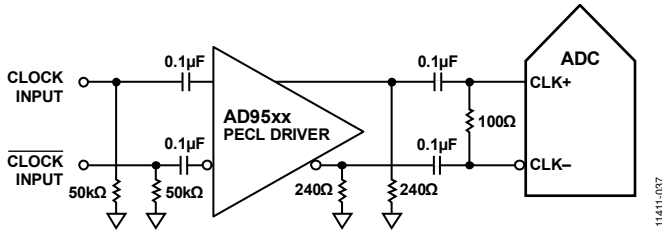


Figure 37. Differential PECL Sample Clock (Up to 625 MHz)

Analog Devices also offers LVDS clock drivers with excellent jitter performance. Figure 38 shows a typical circuit. This illustrates using LVDS drivers such as the AD9510, AD9511, AD9512, AD9513, AD9514, AD9515, the AD9516-0 through AD9516-5 device family, the AD9517-0 through AD9517-4 device family, the AD9518-0 through AD9518-4 device family, the AD9520-0 through AD9520-5 device family, the AD9522-0 through AD9522-5 device family, AD9523, and AD9524.

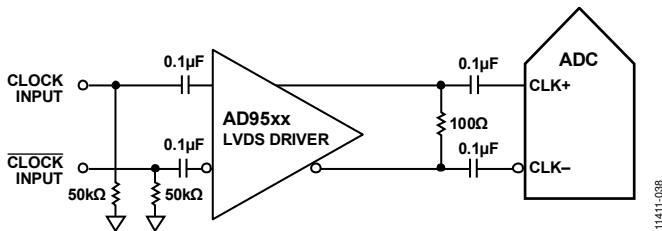


Figure 38. Differential LVDS Sample Clock (Up to 625 MHz)

RF Clock Input Options

The AD6677 RF clock input supports a single-ended clock between 500 MHz to 1.5 GHz. The equivalent RF clock input circuit is shown in Figure 39. The input is self biased to 0.9 V and is typically ac-coupled. The input has a typical input impedance of 10 kΩ in parallel with 0.5 pF at the RFCLK pin.

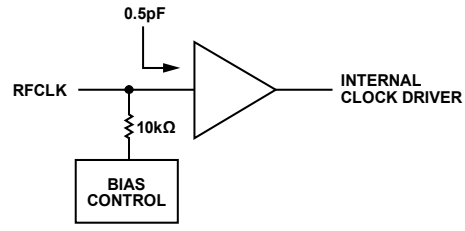


Figure 39. Equivalent RF Clock Input Circuit

It is recommended that the RF clock input of the AD6677 be driven with a PECL or sine wave signal with a minimum signal amplitude of 600 mV p-p. Regardless of the type of signal used, clock source jitter is of the most concern, as described in the Jitter Considerations section. Figure 40 shows the preferred method of clocking when using the RF clock input on the AD6677. Due to the high frequency nature of the signal, it is recommended to use a 50 Ω transmission line to route the clock signal to the RF clock input of the AD6677 and terminate the transmission line close to the RF clock input.

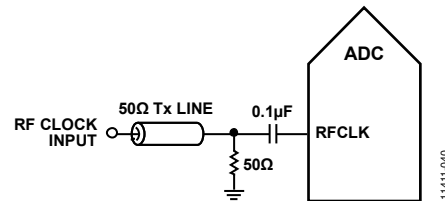


Figure 40. Typical RF Clock Input Circuit

Figure 41 shows the RF clock input of the AD6677 being driven from the LVPECL outputs of the AD9515. The differential LVPECL output signal from the AD9515 is converted to a single-ended signal using an RF balun or RF transformer. The RF balun configuration is recommended for clock frequencies associated with the RF clock input.

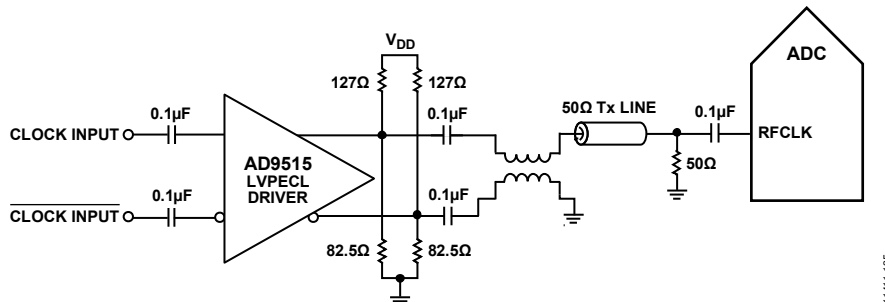


Figure 41. Differential PECL RF Clock Input Circuit

Input Clock Divider

The AD6677 contains an input clock divider with the ability to divide the Nyquist input clock by integer values between 1 and 8. The RF clock input uses an on-chip predivider to divide the clock input by four before it reaches the 1 to 8 divider. This allows higher input frequencies to be achieved on the RF clock input. The divide ratios can be selected using Address 0x09 and Address 0x0B. Address 0x09 sets the RF clock input and Address 0x0B can set the divide ratio of the 1 to 8 divider for both the RF clock input and the Nyquist clock input. For divide ratios other than 1, the duty cycle stabilizer is automatically enabled.

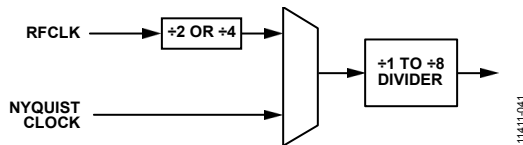


Figure 42. AD6677 Clock Divider Circuit

The AD6677 clock divider can be synchronized using the external SYSREF input. Bit 1 and Bit 2 of Address 0x3A allow the clock divider to be resynchronized on every SYSREF signal or only on the first signal after the register is written. A valid SYSREF causes the clock divider to reset to the initial state. This synchronization feature allows multiple devices to align the clock dividers to guarantee simultaneous input sampling.

Clock Duty Cycle

Typical high speed ADCs use both clock edges to generate a variety of internal timing signals and, as a result, may be sensitive to clock duty cycle. Commonly, a $\pm 5\%$ tolerance is required on the clock duty cycle to maintain dynamic performance characteristics.

The AD6677 contains a DCS that retimes the nonsampling (falling) edge, providing an internal clock signal with a nominal 50% duty cycle. This allows the user to provide a wide range of clock input duty cycles without affecting the performance of the AD6677.

Jitter on the rising edge of the input clock is still of paramount concern and is not reduced by the DCS. The duty cycle control loop does not function for clock rates of less than 40 MHz nominally. The loop has a time constant associated with it that must be considered when the clock rate can change dynamically. A wait time of 1.5 μs to 5 μs is required after a dynamic clock frequency increase or decrease before the DCS loop is relocked to the input signal. During the time that the loop is not locked, the DCS loop is bypassed, and the internal device timing is dependent on the duty cycle of the input clock signal. In such applications, it may be appropriate to disable the DCS. In all other applications, enabling the DCS circuit is recommended to maximize ac performance.

Jitter Considerations

High speed, high resolution ADCs are sensitive to the quality of the clock input. The degradation in SNR at a given input frequency (f_{IN}) due to jitter (t_j) can be calculated by

$$SNR_{HF} = -10 \log[(2\pi \times f_{IN} \times t_{jRMS})^2 + 10^{(-SNR_{LF}/10)}]$$

In the equation, the rms aperture jitter represents the root-mean-square of all jitter sources, which include the clock input, the analog input signal, and the ADC aperture jitter specification. IF undersampling applications are particularly sensitive to jitter, as shown in Figure 43.

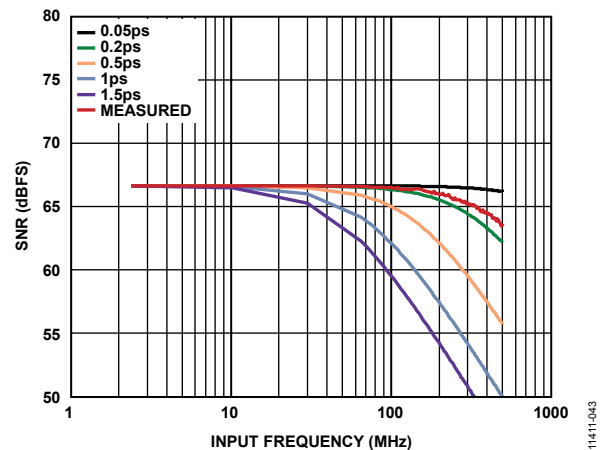


Figure 43. SNR vs. Input Frequency and Jitter

Treat the clock input as an analog signal in cases where aperture jitter may affect the dynamic range of the AD6677. Separate the power supplies for the clock drivers from the ADC output driver supplies to avoid modulating the clock signal with digital noise. Low jitter, crystal controlled oscillators make the best clock sources. If the clock is generated from another type of source (by gating, dividing, or another method), retime it by using the original clock at the last step.

Refer to the Application Note AN-501, *Aperture Uncertainty and ADC System Performance*, and the Application Note AN-756, *Sampled Systems and the Effects of Clock Phase Noise and Jitter*, for more information about jitter performance as it relates to ADCs.

POWER DISSIPATION AND STANDBY MODE

As shown in Figure 44, the power dissipated by the AD6677 is proportional to the sample rate. The data in Figure 44 was taken using the same operating conditions as those used for the Typical Performance Characteristics section. I_{DVDD} in Figure 44 is a summation of I_{DVDD} and I_{DRVDD} .

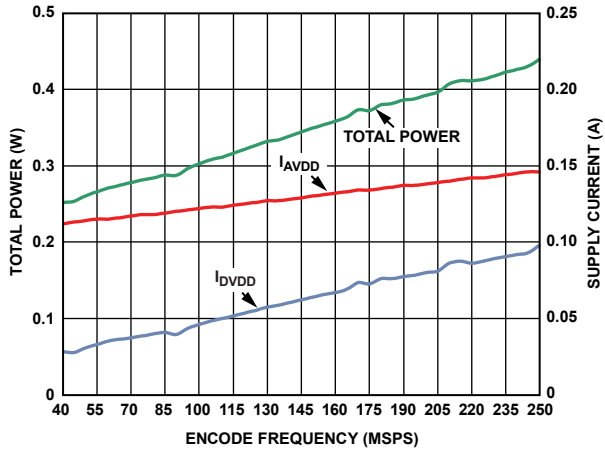


Figure 44. Power vs. Encode Rate

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By asserting PDWN (either through the SPI port or by asserting the PDWN pin high), the AD6677 is placed in power-down mode. In this state, the ADC typically dissipates about 9 mW. Asserting the PDWN pin low returns the AD6677 to the normal operating mode.

Low power dissipation in power-down mode is achieved by shutting down the reference, reference buffer, biasing networks, and clock. Internal capacitors are discharged when entering power-down mode and then must be recharged when returning to normal operation. As a result, wake-up time is related to the time spent in power-down mode, and shorter power-down cycles result in proportionally shorter wake-up times.

When using the SPI port interface, the user can place the ADC in power-down mode or standby mode. Standby mode allows the user to keep the internal reference circuitry powered when faster wake-up times are required. See the Memory Map Register Descriptions section and the Application Note AN-877, *Interfacing to High Speed ADCs via SPI*, for additional details.

NOISE SHAPING REQUANTIZER

The AD6677 features a NSR to allow higher than 11-bit SNR to be maintained in a subset of the Nyquist band. The harmonic performance of the receiver is unaffected by the NSR feature. When enabled, the NSR contributes an additional 0.6 dB of loss to the input signal, such that a 0 dBFS input is reduced to -0.6 dBFS at the output pins.

Two different bandwidth modes are provided; the mode can be selected from the SPI port. In each of the two modes, the center frequency of the band can be tuned such that IFs can be placed anywhere in the Nyquist band.

22% BANDWIDTH MODE (>40 MHz AT 184.32 MSPS)

The first bandwidth mode offers excellent noise performance over 22% of the ADC sample rate (44% of the Nyquist band) and can be centered by setting the NSR mode bit in the NSR control register (Address 0x3C) to 0. In this mode, the useful frequency range can be set using the 6-bit tuning word in the NSR tuning words register (Address 0x3E). There are 57 possible tuning words (TW); each step is 0.5% of the ADC sample rate. The following three equations describe the left band edge (f_0), the channel center (f_{CENTER}), and the right band edge (f_1), respectively:

$$f_0 = f_{ADC} \times 0.005 \times TW$$

$$f_{CENTER} = f_0 + 0.11 \times f_{ADC}$$

$$f_1 = f_0 + 0.22 \times f_{ADC}$$

Figure 45 to Figure 47 show the typical spectrum that can be expected from the AD6677 in the 22% bandwidth mode for three different tuning words.

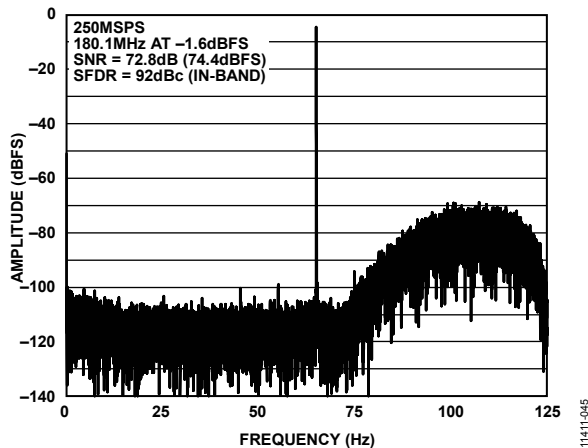


Figure 45. 22% Bandwidth Mode, Tuning Word = 13

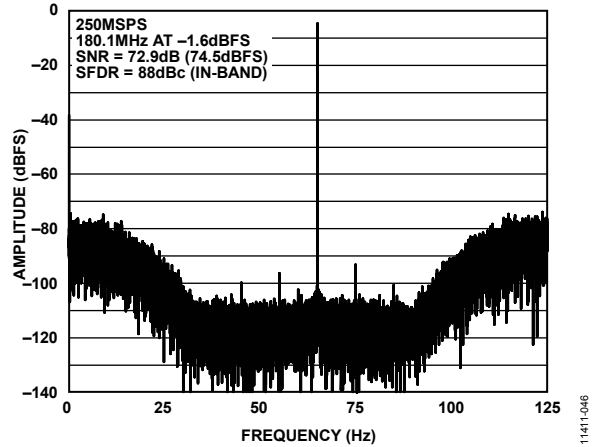


Figure 46. 22% Bandwidth Mode, Tuning Word = 28 ($f_s/4$ Tuning)

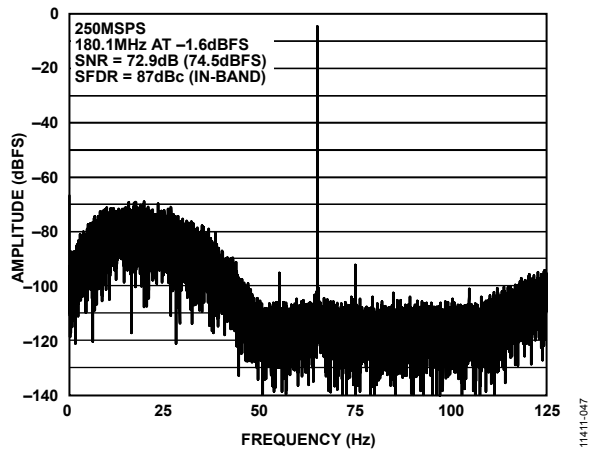


Figure 47. 22% Bandwidth Mode, Tuning Word = 41

33% BANDWIDTH MODE (>60 MHz AT 184.32 MSPS)

The second bandwidth mode offers excellent noise performance over 33% of the ADC sample rate (66% of the Nyquist band) and can be centered by setting the NSR mode bit in the NSR control register (Address 0x3C) to 1. In this mode, the useful frequency range can be set using the 6-bit tuning word in the NSR tuning register (Address 0x3E). There are 57 possible tuning words (TW); each step is 0.5% of the ADC sample rate. The following three equations describe the left band edge (f_0), the channel center (f_{CENTER}), and the right band edge (f_1), respectively:

$$f_0 = f_{ADC} \times .005 \times TW$$

$$f_{CENTER} = f_0 + 0.165 \times f_{ADC}$$

$$f_1 = f_0 + 0.33 \times f_{ADC}$$

Figure 48 to Figure 50 show the typical spectrum that can be expected from the AD6677 in the 33% bandwidth mode for three different tuning words.

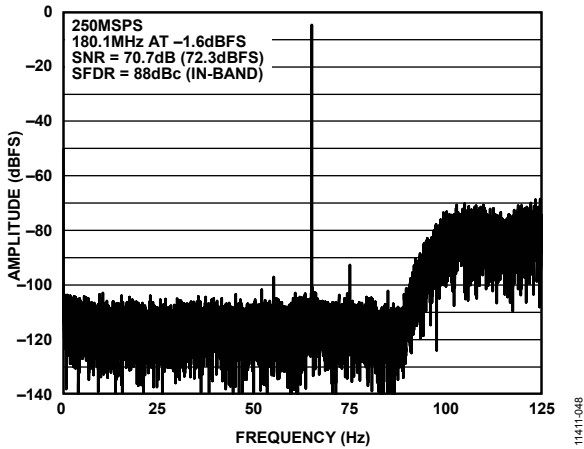


Figure 48. 33% Bandwidth Mode, Tuning Word = 5

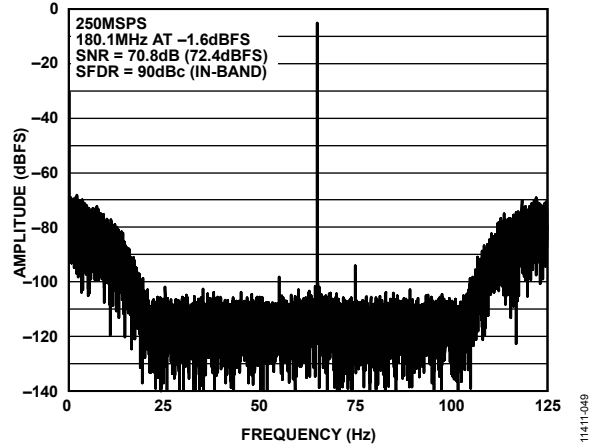


Figure 49. 33% Bandwidth Mode, Tuning Word = 17 ($f_s/4$ Tuning)

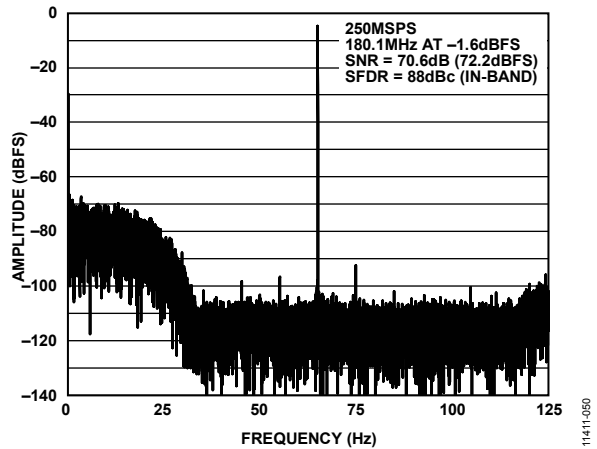


Figure 50. 33% Bandwidth Mode, Tuning Word = 27

DIGITAL OUTPUTS

JESD204B TRANSMIT TOP LEVEL DESCRIPTION

The AD6677 digital output uses the JEDEC Standard No. JESD204B, *Serial Interface for Data Converters*. JESD204B is a protocol to link the AD6677 to a digital processing device over a serial interface of up to 5 Gbps link speeds. The benefits of the JESD204B interface include a reduction in required board area for data interface routing and the enabling of smaller packages for converter and logic devices. The AD6677 supports single or dual lane interfaces.

JESD204B Overview

The JESD204B data transmit block assembles the parallel data from the ADC into frames and uses 8B/10B encoding as well as optional scrambling to form serial output data. Lane synchronization is supported using special characters during the initial establishment of the link and additional synchronization is embedded in the data stream thereafter. A matching external receiver is required to lock onto the serial data stream and recover the data and clock. For additional details on the JESD204B interface, refer to the JESD204B standard.

The AD6677 JESD204B transmit block maps the output of the ADC over a single link. The link is configured to use a single pair of serial differential outputs that is called a lane. The JESD204B specification refers to a number of parameters to define the link, and these parameters must match between the JESD204B transmitter (AD6677 output) and receiver.

The JESD204B link is described according to the following parameters:

- S = samples transmitted per single converter per frame cycle (AD6677 value = 1)
- M = number of converters per converter device (AD6677 value = 1)
- L = number of lanes per converter device (AD6677 value = 1)
- N = converter resolution (AD6677 value = 11)
- N' = total number of bits per sample (AD6677 value = 16)
- CF = number of control words per frame clock cycle per converter device (AD6677 value = 0)
- CS = number of control bits per conversion sample (configurable on the AD6677 up to 2 bits)
- K = number of frames per multiframe (configurable on the AD6677)
- HD = high density mode (AD6677 value = 0)
- F = octets/frame (AD6677 value = 2)
- C = control bit (overrange, overflow, underflow; available on the AD6677)
- T = tail bit (available on the AD6677)
- SCR = scrambler enable/disable (configurable on the AD6677)
- FCHK = checksum for the JESD204B parameters (automatically calculated and stored in register map)

Figure 51 shows a simplified block diagram of the AD6677 JESD204B link. The AD6677 is configured to use one converter and one lane. Converter data is output to SERDOUT0+/SERDOUT0-. The AD6677 allows for other configurations such as combining the outputs of both converters onto a single lane or changing the mapping of the A and B digital output paths. These modes are set up through a quick configuration register in the register map, along with additional customizable options.

By default, in the AD6677, the 11-bit converter word is divided into two octets (8 bits of data). Bit 10 (MSB) through Bit 3 are in the first octet. The second octet contains Bit 2 through Bit 0 (LSB), followed by three bits that can be programmed as 0 or pseudo-random numbers with two tail bits added to fill the second octet. The tail bits can be configured as zeros, a pseudo-random number sequence, or control bits indicating overrange, underrange, or valid data conditions.

The two resulting octets can be scrambled. Scrambling is optional, however, it is available to avoid spectral peaks when transmitting similar digital data patterns. The scrambler uses a self synchronizing, polynomial-based algorithm defined by the $1 + x^{14} + x^{15}$ equation. The descrambler in the receiver must be a self synchronizing version of the scrambler polynomial.

The two octets are then encoded with an 8B/10B encoder. The 8B/10B encoder works by taking eight bits of data (an octet) and encoding them into a 10-bit symbol. Figure 52 shows how the 11-bit data is taken from the ADC, the tail bits are added, the two octets are scrambled, and how the octets are encoded into two 10-bit symbols. Figure 52 illustrates the default data format.

At the data link layer, in addition to the 8B/10B encoding, the character replacement allows the receiver to monitor frame alignment. The character replacement process occurs on the frame and multiframe boundaries. Implementation depends on which boundary is occurring and if scrambling is enabled.

If scrambling is disabled, the following applies:

- If the last scrambled octet of the last frame of the multiframe equals the last octet of the previous frame, the transmitter replaces the last octet with the control character /A/ = /K28.3/.
- On other frames within the multiframe, if the last octet in the frame equals the last octet of the previous frame, the transmitter replaces the last octet with the control character /F/ = /K28.7/.

If scrambling is enabled, the following applies:

- If the last octet of the last frame of the multiframe equals 0x7C, the transmitter replaces the last octet with the control character /A/ = /K28.3/.
- On other frames within the multiframe, if the last octet equals 0xFC, the transmitter replaces the last octet with the control character /F/ = /K28.7/.